ALPHA & OMEGA SEMICONDUCTOR, INC.

August 2002

AO6404
N-Channel Enhancement Mode Field Effect Transistor

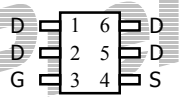
General Description

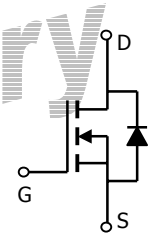
The AO6404 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V while retaining a 12V $V_{GS(MAX)}$ rating.

Features

V_{DS} (V) = 20V
I_D = 8.5A
$R_{DS(ON)}$ < 15mΩ (V_{GS} = 10V)
$R_{DS(ON)}$ < 16mΩ (V_{GS} = 4.5V)
$R_{DS(ON)}$ < 22mΩ (V_{GS} = 2.5V)
$R_{DS(ON)}$ < 30mΩ (V_{GS} = 1.8V)

TSOP-6
Top View





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	±12	V
Continuous Drain Current [A]	T_A=25°C	I_D	8.5	A
	T_A=70°C		7.3	
Pulsed Drain Current [B]		I_{DM}	30	
Power Dissipation [A]	T_A=25°C	P_D	2	W
	T_A=70°C		1.44	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	45	62.5	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		70	110	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	33	50	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	20			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=16V, V_{GS}=0V			10	µA
		T_J=55°C			25	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±12V			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	0.5	0.75	1	V
$I_{D(ON)}$	On state drain current	V_{GS}=4.5V, V_{DS}=5V	30			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=8.5A		12	15	mΩ
		T_J=125°C				
		V_{GS}=4.5V, I_D=5A		13.5	16	mΩ
		V_{GS}=2.5V, I_D=4A		17.5	22	mΩ
		V_{GS}=1.8V, I_D=3A		24.5	30	mΩ
g_{FS}	Forward Transconductance					S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.73	1	V
I_S	Maximum Body-Diode Continuous Current				2.9	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=10V, f=1MHz		1690		pF
C_{oss}	Output Capacitance			230		pF
C_{rss}	Reverse Transfer Capacitance			184		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		1.6		Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	V_{GS}=4.5V, V_{DS}=10V, I_D=8.5A		17.8		nC
Q_{gs}	Gate Source Charge			1.76		nC
Q_{gd}	Gate Drain Charge			5		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=10V, R_L=1.2Ω, R_{GEN}=3Ω		3.3		ns
t_r	Turn-On Rise Time			5.9		ns
$t_{D(off)}$	Turn-Off DelayTime			44		ns
t_f	Turn-Off Fall Time			7.7		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=8.5A, dI/dt=100A/µs		22		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=8.5A, dI/dt=100A/µs		9.8		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any a given application depends on the user's specific board design. The current rating is based on the t≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80µs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.